

PCN20250731001.1
Qualification of additional Assembly sites for select SOT-SC70 devices
Change Notification / Sample Request

Date: July 31, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20250731001.1**Attachment: 1****Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74LVC1G17DCKR	SN74LVC1G17DCKR
SN74LVC1G10DCKR	SN74LVC1G10DCKR
SN74LVC1G132DCKR	NULL
SN74AUP1T57DCKR	SN74AUP1T57DCKR
SN74LVC1G32DCKR	SN74LVC1G32DCKR
SN74LVC1G386DCKR	NULL
SN74LVC2G14DCKR	SN74LVC2G14DCKR
SN74LVC1G3208DCKR	SN74LVC1G3208DCKR
SN74LVC1G07DCKR	SN74LVC1G07DCKR
SN74AUC1G86DCKR	NULL
SN74LVC1G0832DCKR	NULL
SN74AUP1T58DCKR	SN74AUP1T58DCKR

Technical details of this Product Change follow on the next page(s).

PCN Number:	PCN#20250731001.1	PCN Date:	July 31, 2025
Title:	Qualification of additional Assembly sites for select SOT-SC70 devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	October 29, 2025	Sample requests accepted until:	September 29, 2025*
*Sample requests received after September 29, 2025 will not be supported.			
Change Type:			
<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/>	Wafer Fab Material
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the qualification of additional Assembly sites for devices listed below in the product affected section. Construction information and all assembly sites are as follows:

SOT-SC70 Build Sites	
Assembly Sites	ASEWH, HFTFAT, HNA, TFME, UTL2, CDAT, TIEMA
Mount Compound	4226215
	SID#A-21
	SID#400180
	SID#A-03
	SID#1120999A2
	4221460
	SID#A-16
	4207123
Mold Compound	4229877
	SID# R-21
	SID# R-27
	4209002
	8095181
	SID#450179
	SID# R-07
	SID#450042
Lead frame Finish	4222198
	SID# R-32
Bond Wire (mil)	NIPDAU, Matte Sn

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS

REACH

Green Status

IEC 62474

<input checked="" type="checkbox"/> No Change			
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Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
ASEWH	AWH	CHN	Weihai
HFTFAT	HFT	CHN	Hefei
TFME	NFM	CHN	Chongchuan
HNA	HNT	THA	Ayutthaya
UTL2	NSE	THA	Bangkok
TIEMA	NS2	THA	Bangpakong
CDAT	CDA	CHN	Chengdu

Sample product shipping label (not actual product label)



Product Affected:

SN74AUC1G19DCKR	SN74AUP1T98DCKR	SN74LVC1G17DCKR	
SN74AUC1G86DCKR	SN74LVC1G07DCKR	SN74LVC1G3208DCKR	
SN74AUC2GU04DCKR	SN74LVC1G0832DCKR	SN74LVC1G32DCKR	
SN74AUP1T57DCKR	SN74LVC1G10DCKR	SN74LVC1G386DCKR	
SN74AUP1T58DCKR	SN74LVC1G132DCKR	SN74LVC2G14DCKR	

SOT-SC70 Qualification Report

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	TIEMA LMV7275MG/NOPB LMH6601MG/NOPB	HFTFAT TMUX1119DCK
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0
HAST/THB	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0
UHAST/AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (LM4041CIM7X-1.2/NOPB)	3/66/0 (INA210AIDCK)
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	HNA SN74AUP1T34QDCKRQ1 TMUX1119DCK	TFME SN74LVC1G17DCKR
TC	Temperature Cycling - 65/150C Or Temperature Cycling - 55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0
HAST/ THB	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0
UHAST/AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (TL431BDCK)	3/66/0
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	ASEWH TPD4E1U06DCK	CDAT LMV721IDCK TLV9061IDBV	UTL2 TLV70228DCK
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0	3/231/0
HAST/THB	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0	3/66/0 (REF3312AIDCK)
MQ	Manufacturability	-	Pass	Pass	Pass

All qualification devices in the tables are qualified at L1-260C MSL rating.

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable
- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
- Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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